

DPW

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**



**Appl. No.** : **10/734,195**  
**Applicant** : **Kwun-Yao Ho et al.**  
**Filed** : **December 15, 2003**  
**Title** : **HIGH-DENSITY MULTICHIP MODULE**  
**PACKAGE**  
**TC/A.U.** : **2813**  
**Examiner** : **BRYANT, DELORIS S**  
**Docket No.** : **025796-00014**

Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

In response to the Official Action mailed September 14, 2005. Applicants respectfully request that the Examiner reconsider the amended application according to the following remarks.

Please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begin on page 4 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.